

RSFAL - RSFML



0.5 AMP. Surface Mount Fast Recovery Rectifiers Sub SMA

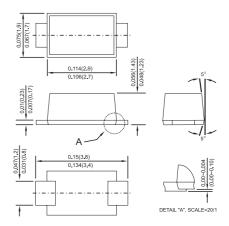


Features

- For surface mounted application
- ♦ Glass passivated junction chip
- High temperature metallurgically bonded construction
- Plastic material used carries Underwriters Laboratory Classification 94V-0
- Fast switching for high efficiency \diamond
- High temperature soldering: 260 °C / 10 seconds at terminals

Mechanical Data

- Cases: Sub SMA plastic case
- Terminals: Pure tin plated, Lead free.
- Polarity: Indicated by cathode band
- Packing: 12mm tape per EIA STD RS-481
- Weight: 15mg



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

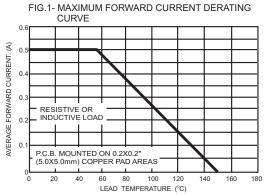
Type Number	Symbol	RSF AL	RSF BL	RSF DL	RSF GL	RSF JL	RSF KL	RSF ML	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Marking Code (Note 4)		FALYM	FBLYM	FDLYM	FGLYM	FJLYM	FKLYM	FMLYM	
Maximum Average Forward Rectified Current See Fig. 1 @T _L =55°C	$I_{(AV)}$	0.5							Α
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	10							Α
Max. Full Load Reverse Current, Full cycle Average T _A =55 °C	I_{R}	30							uA
Maximum Instantaneous Forward Voltage @ 0.5A	V_{F}	1.3							V
Maximum DC Reverse Current @ T _A =25 °C at Rated DC Blocking Voltage @ T _A =125 °C	I_R	5 50							uA uA
Maximum Reverse Recovery Time (Note 1)	Trr	150 250 500)	nS	
Typical Junction Capacitance (Note 2)	Cj	4.0						pF	
Non-repetitive Peak Reverse Avalanche Energy L=120mH max prior to Surge, Inductive load Switched off	E _{RSM}	10 7					mJ		
Typical Thermal Resistance (Note 3)	R _{øJA} R _{øJL}	150 32						°C /W	
Operating Temperature Range	T_J	-55 to +150						°C	
Storage Temperature Range	Tstg	-55 to +150							°C

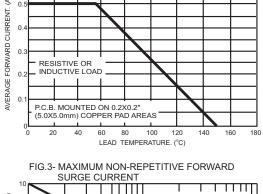
Notes: 1. Reverse Recovery Test Conditions: IF=0.5A, IR=1.0A, IRR=0.25A

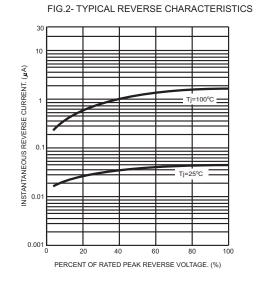
- 2. Measured at 1 MHz and Applied VR=4.0 Volts
 3. Measured on P.C.Board with 0.2" x 0.2" (5mm x 5mm) Copper Pad Areas.
 4. FALYM: F=0.5A, A=50V, L-Low Profile, Y-Year Code, M-Month Code.

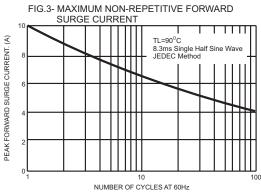


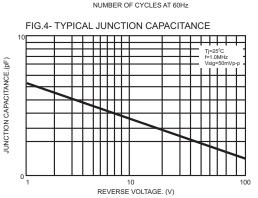
RATINGS AND CHARACTERISTIC CURVES (RSFAL THRU RSFML)











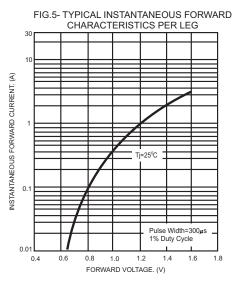


FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM

